

Application No.: 10/695,018

Docket No.: JCLA11476

**REMARKS****Present Status of the Application**

This is a full and timely response to the outstanding final Office Action mailed on June 30, 2004. The Office Action has rejected claims 1-13 under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Liu et al. (US Patent Application 2004/0032019).

Claims 1-13 remain pending of which claims 1 and 9 have been amended to more accurately describe the invention. It is believed that no new matter is added by way of these amendments made to the claims or otherwise to the application.

Applicant has most respectfully considered the remarks set forth in this Office Action. Regarding the obvious rejections, it is however strongly believed that the cited references are deficient to adequately teach the claimed features as recited in the presently pending claims. The reasons that motivate the above position of the Applicant are discussed in detail hereafter, upon which reconsideration of the claims is most earnestly solicited.

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**Response to 35 U.S.C. 103 rejection**

*Claims 1-13 are rejected under 35 U.S.C. 103(a) as being unpatentable over the AAPA in view of Liu et al. (US 2004.0032019, Liu hereinafter).*

Applicants respectfully submit that APAF in view of Yano is legally deficient for the purpose of rendering claims 1 or 9 unpatentable because the references, taken alone or combined, fail teach or suggest each and every element recited in the claims.

The present invention teaches, among other things, one of the conducting wire connects at least one of the die pads to at least one of the electrodes of the passive component, wherein the electrodes are electrically and physically connected to said power pad and said ground pad, respectively. Since the electrodes of the passive component in the present invention are electrically and physically connected to the power pad or the ground pad, connecting the die and the carrier only requires having the conducting wire to connect between the die pads and the electrodes. Accordingly, an additional wiring and/or transmission path for having the conducting wire to cross over the passive component to connect the die pad with the power pad or the ground pad as taught in the AAPA or having an additional bonding wire 170 to connect the bonding section 150 of the capacitor 120 to the power ring 106 as taught in Liu is obviated. Furthermore, Liu teaches a dielectric bonding section 150 on the capacitor 120, wherein the connection between the die and the carrier is through a first bonding wire 160 between the die pad and the dielectric bonding section 150 and the second bonding wire 170 between the dielectric bonding section 150 and the power ring 106. Therefore, the bonding wires of Liu are

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not electrically connected to the capacitor 120, whereas the conducting wires of the instant case are electrically connected to the electrode of the passive component.

Accordingly, in view of the foregoing reasons, even if there were motivation to combine AAPA with Yano, the combination still fails to teach or suggest the claimed invention.

Accordingly, the withdrawal of the rejection and the allowance of claims 1 and 9 earnestly requested. Because claims 2-8, 10-13 are dependent upon claims 1 and 9, respectively, the same reasons as discussed above also apply to these claims.

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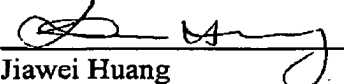
**CONCLUSION**

For at least the foregoing reasons, it is believed that the presently pending claims 1-19 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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